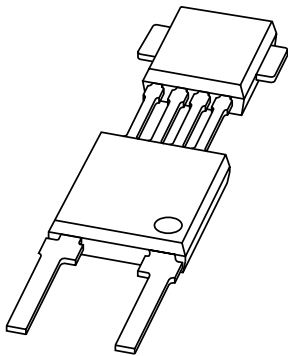


# DATA SHEET



## **KMI15/2**

### **Integrated rotational speed sensor**

Product specification  
Supersedes data of 2000 Jun 26

2000 Sep 05

# Integrated rotational speed sensor

KMI15/2

## FEATURES

- Digital current output signal
- Zero speed capability
- Wide air gap
- Wide temperature range
- Insensitive to vibration
- EMC resistant.

## DESCRIPTION

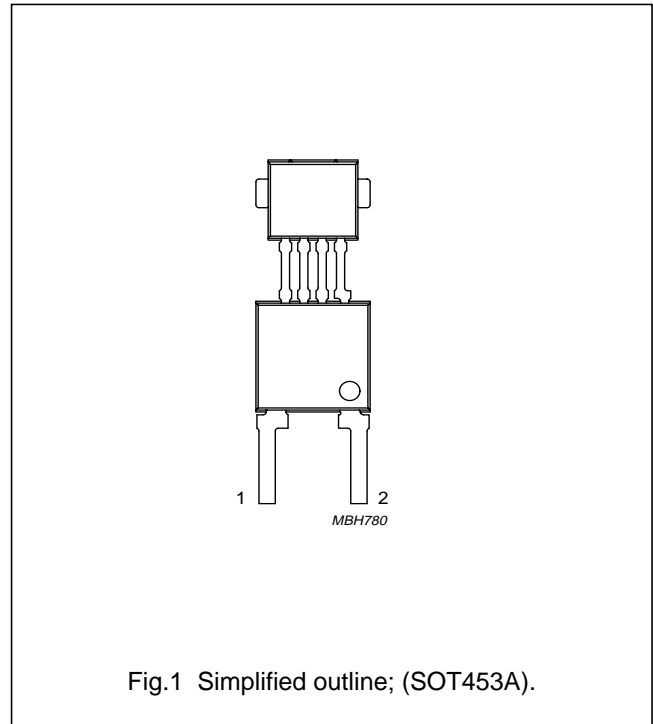
The KMI15/2 sensor detects (rotational) speed and reference mark detection of magnetized targets<sup>(1)</sup>. The sensor consists of a magnetoresistive sensor element, a signal conditioning integrated circuit in bipolar technology and a magnetized ferrite magnet. The frequency of the digital current output signal is proportional to the rotational speed of a gear wheel.

<b>CAUTION</b>
Do not press two or more products together against their magnetic forces.

(1) The sensor contains a customized integrated circuit. Usage in hydraulic brake systems and in systems with active brake control is forbidden. For all other applications, higher temperature versions of up to 150 °C are available on request.

## PINNING

PIN	DESCRIPTION
1	V <sub>CC</sub>
2	V-



## QUICK REFERENCE DATA

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V <sub>CC</sub>	DC supply voltage	0.5	12	16	V
I <sub>CC (low)</sub>	current output signal low	–	7	–	mA
I <sub>CC (high)</sub>	current output signal high	–	14	–	mA
f <sub>t</sub>	operating frequency	0	–	25000	Hz
T <sub>amb</sub>	ambient operating temperature	–40	–	+85	°C

## Integrated rotational speed sensor

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**LIMITING VALUES**

In accordance with Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CC}$	DC supply voltage	$T_{amb} = -40$ to $+85$ °C; $R_L = 115$ $\Omega$	0.5	16	V
$T_{stg}$	storage temperature		-40	+150	°C
$T_{amb}$	operating ambient temperature		-40	+85	°C
$T_{sld}$	soldering temperature	$t \leq 10$ s	-	260	°C
	output short-circuit duration to GND		continuous		

**CHARACTERISTICS** $T_{amb} = 25$  °C;  $V_{CC} = 12$  V;  $f_t = 2$  kHz; test circuit: see Fig.7;  $R_L = 115$   $\Omega$ .

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{CC (low)}$	current output signal low	see Fig.6	5.6	7.0	8.4	mA
$I_{CC (high)}$	current output signal high	see Fig.6	11.2	14.0	16.8	mA
$t_r$	output signal rise time	$C_L = 100$ pF; 10 to 90% value	-	0.5	-	$\mu$ s
$t_f$	output signal fall time	$C_L = 100$ pF; 10 to 90% value	-	0.7	-	$\mu$ s
$t_d$	switching delay time	between stimulation pulse (generated by a coil) and output signal	-	1	-	$\mu$ s
$f_t$	operating frequency	for both rotation directions	0	-	25000	Hz
$H_{sLH}$	magnetic switching field strength		0.05	0.3	0.8	kA/m
$H_{sHL}$	magnetic switching field strength		0.05	0.3	0.8	kA/m
$H_s$	magnetic switching hysteresis		0.15	-	1.6	kA/m

## Integrated rotational speed sensor

## KMI15/2

**FUNCTIONAL DESCRIPTION**

The KMI15/2 sensor is sensitive to magnetic fields. The functional principle is shown in Fig.3. The field lines of a magnetized target are shown in Fig.3 as a straight target (it could also be circular e.g. for rotational speed measurement). If a sensor KMI15/2 is moved as shown in this field, either of the magnetic field components  $H_{sHL}$  or  $H_{sLH}$  is dominant, and forces the sensor to switch to either the high current (14 mA) or to the low current (7 mA). Oscillation of the sensor output signal is avoided by the implementation of a hysteresis into the signal conditioning electronic.

The MR sensor is stabilized by a permanent magnet applying a continuous magnetic field of  $\geq 6$  kA/m to the sensor. If the magnetic field given by the magnetized target errors like frequency doubling might occur. The magnetoresistive sensor element signal is amplified, temperature compensated and forwarded to a Schmitt-trigger in the conditioning integrated circuit (Figs 4 and 5). The digital output signal levels (Fig.6) are independent of the magnetic field condition. A (2-wire) output current enables safe transfer of the sensor signal to the detecting circuit (Fig.7). The integrated circuit housing is separated from the sensor element housing to optimize the sensor behaviour at high temperatures.

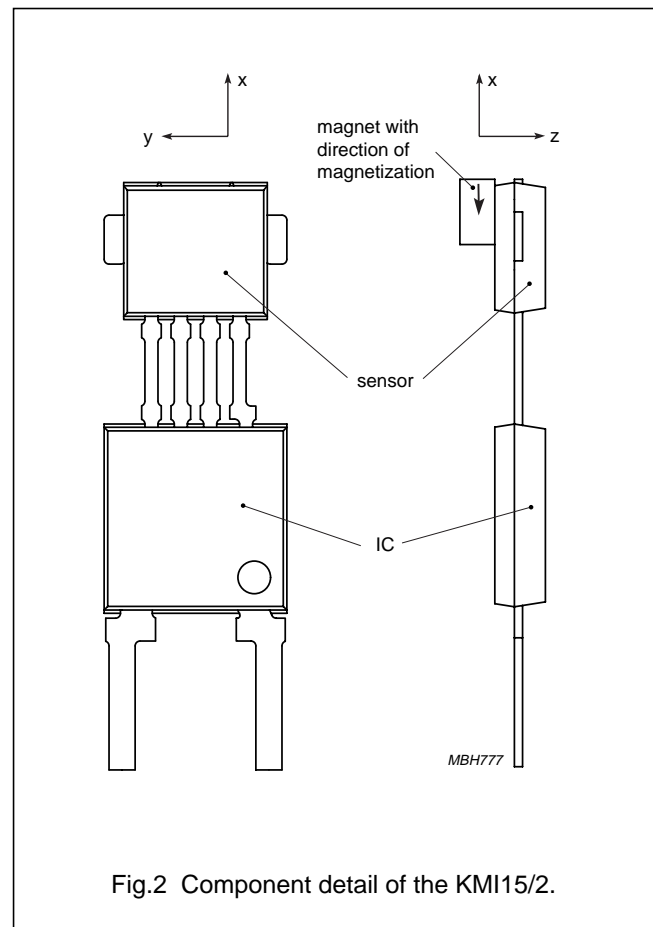


Fig.2 Component detail of the KMI15/2.

# Integrated rotational speed sensor

KMI15/2

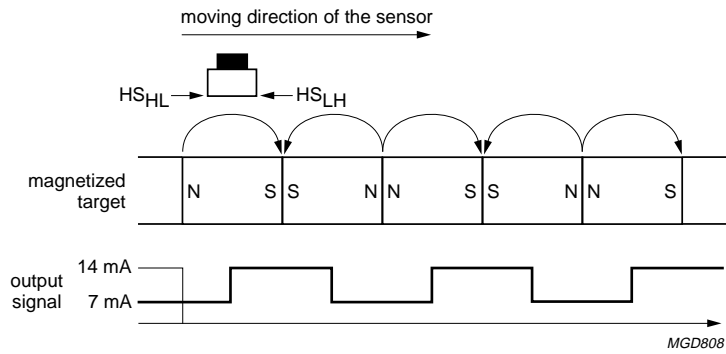


Fig.3 Functional principle of KMI15/2.

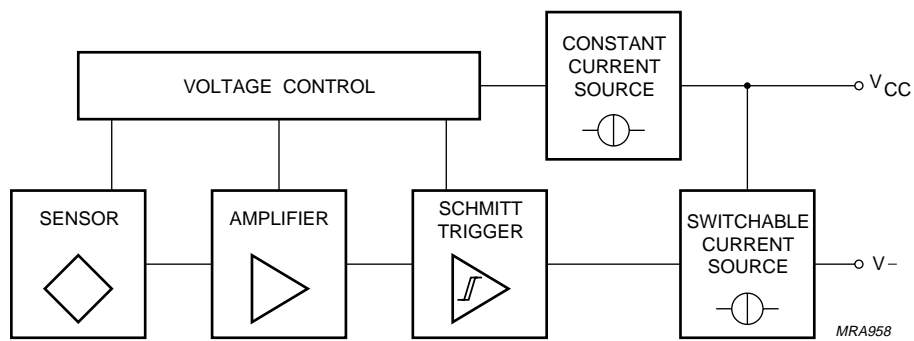
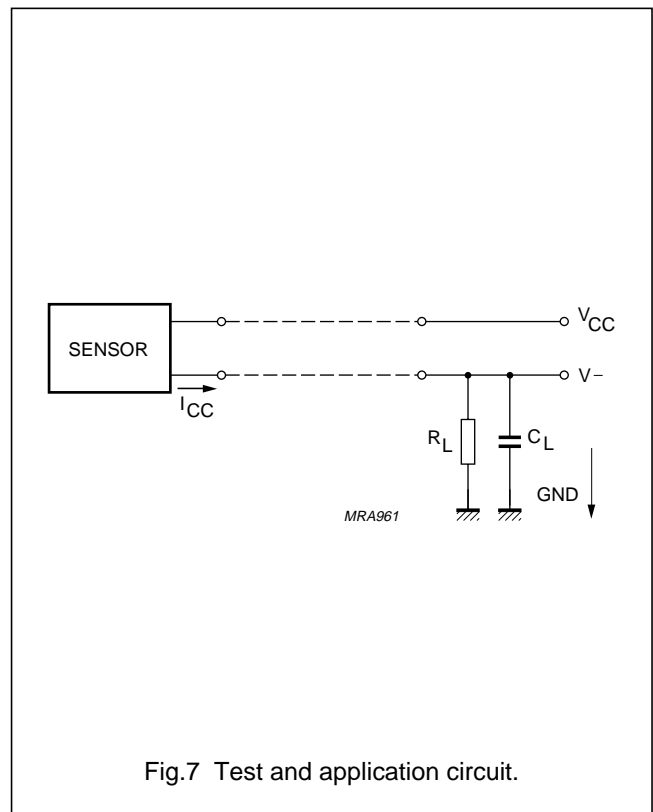
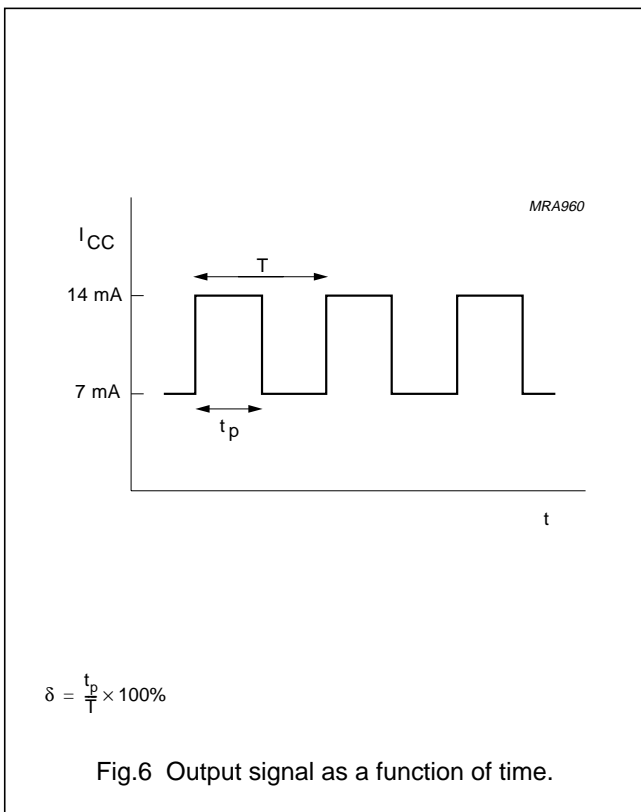
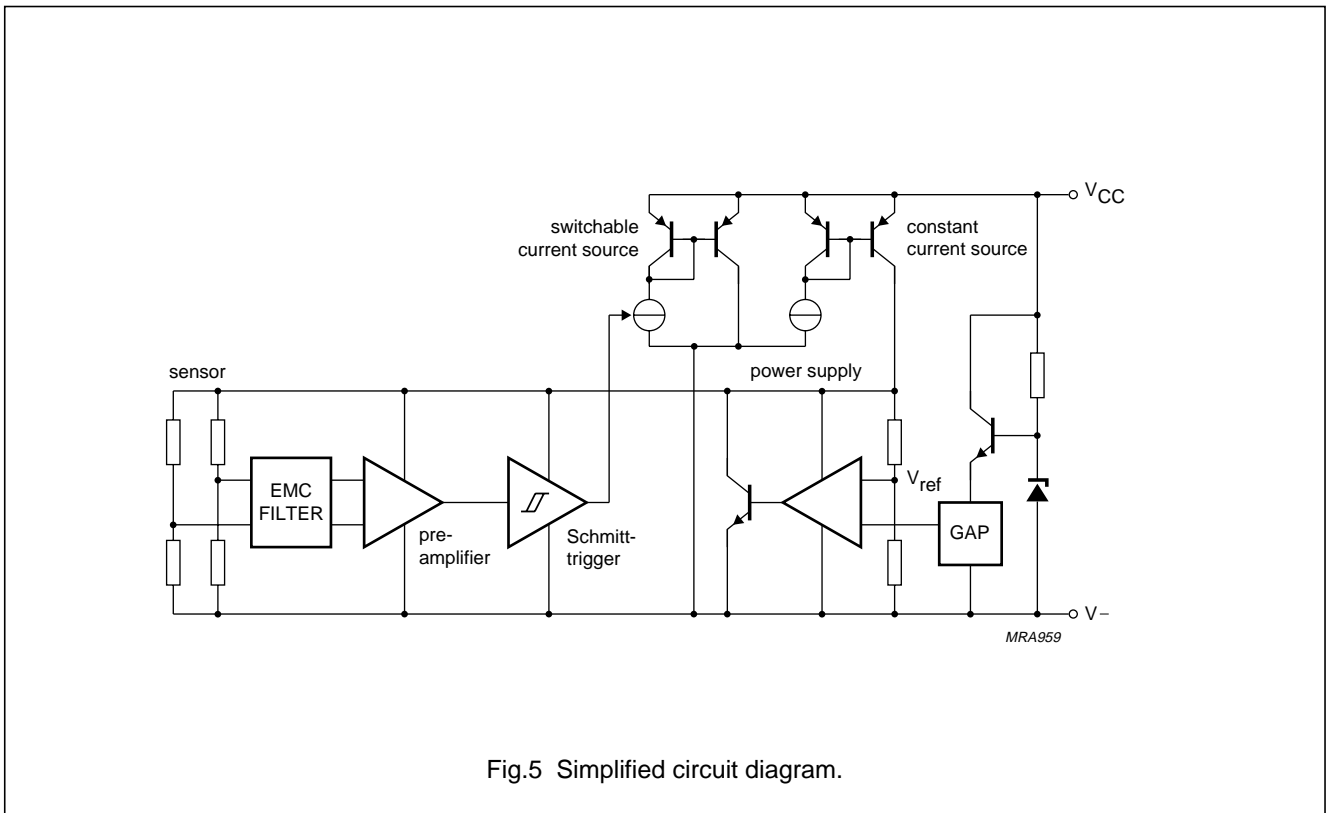


Fig.4 Block diagram.

Integrated rotational speed sensor

KMI15/2



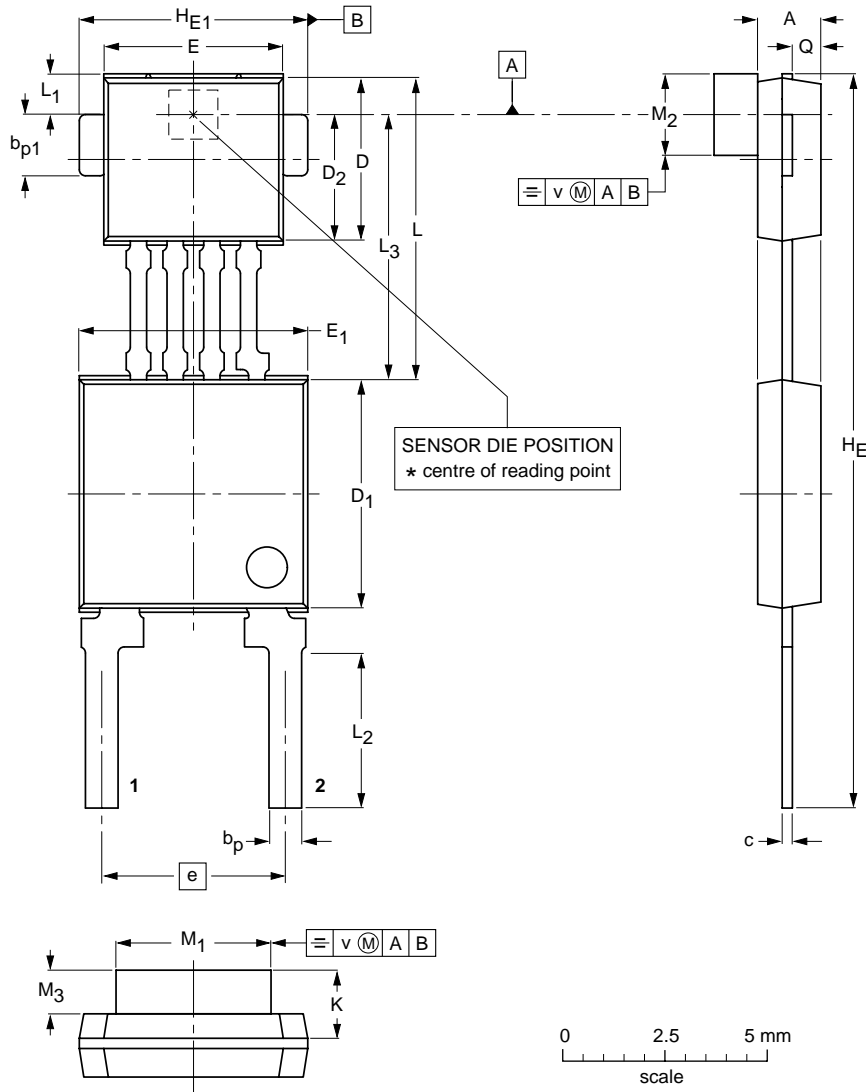
Integrated rotational speed sensor

KMI15/2

PACKAGE OUTLINE

Plastic single-ended multi-chip package;  
magnetized ferrite magnet (3.8 x 2 x 0.8 mm); 4 interconnections; 2 in-line leads

SOT453A



DIMENSIONS (mm are the original dimensions)

UNIT	A <sup>(1)</sup>	b <sub>p</sub>	b <sub>p1</sub>	c	D <sup>(2)</sup>	D <sub>1</sub> <sup>(2)</sup>	D <sub>2</sub> <sup>(2)</sup>	E <sup>(2)</sup>	E <sub>1</sub> <sup>(2)</sup>	e	H <sub>E</sub>	H <sub>E1</sub>	K <sub>max.</sub>	L	L <sub>1</sub>	L <sub>2</sub>	L <sub>3</sub>	M <sub>1</sub>	M <sub>2</sub>	M <sub>3</sub> <sup>(1)</sup>	Q	v
mm	1.7 1.4	0.8 0.7	1.57 1.47	0.3 0.24	4.1 3.9	5.7 5.5	3.15 2.95	4.5 4.3	5.7 5.5	4.6 4.4	18.2 17.8	5.6 5.5	1.67	7.55 7.25	1.2 0.9	3.9 3.5	6.55 6.35	3.9 3.7	2.1 1.9	0.9 0.7	0.75 0.65	0.25

Notes

1. Glue thickness not included.
2. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT453A						99-09-22- 00-08-31

## Integrated rotational speed sensor

KMI15/2

## DATA SHEET STATUS

DATA SHEET STATUS	PRODUCT STATUS	DEFINITIONS <sup>(1)</sup>
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

## Note

1. Please consult the most recently issued data sheet before initiating or completing a design.

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Integrated rotational speed sensor

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**NOTES**

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**NOTES**

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